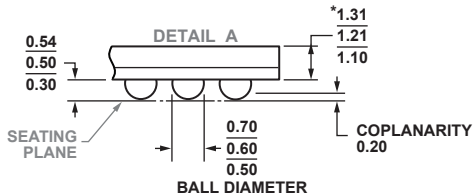
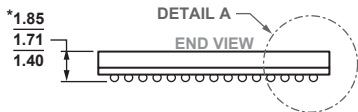
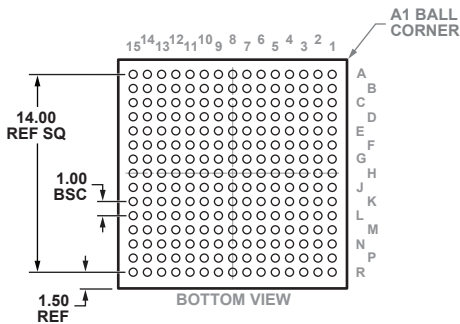
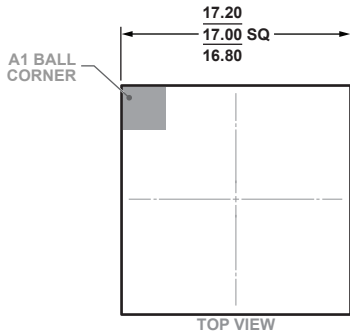


225-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-225-1)

Dimensions shown in millimeters



***COMPLIANT TO JEDEC STANDARDS MO-192-AAF-2
WITH THE EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.**